

ABSTRACT OF THE DISCLOSURE

Process solutions comprising one or more surfactants are used to reduce the  
5 number of defects in the manufacture of semiconductor devices. In certain preferred  
embodiments, the process solution of the present invention may reduce defects when  
employed as a rinse solution either during or after the development of the CMP  
processing. Also disclosed is a method for reducing the number of defects on a plurality  
of post-CMP processed substrates employing the process solution of the present  
10 invention.